

Gate Driver BM60212FV-C Evaluation Board BM60212FV-EVK001

User's Guide

< High Voltage Safety Precautions >

Please note that this document covers only the BM60212FV-C evaluation board (BM60212FV-EVK001) and its functions. For additional information, please refer to the datasheet.

To ensure safe operation, please carefully read all precautions before handling the evaluation board



Depending on the configuration of the board and voltages used,

Potentially lethal voltages may be generated.

Therefore, please make sure to read and observe all safety precautions described in the red box below.

Before Use

- [1] Verify that the parts/components are not damaged or missing (i.e. due to the drops).
- [2] Check that there are no conductive foreign objects on the board.
- [3] Be careful when performing soldering on the module and/or evaluation board to ensure that solder splash does not occur.
- [4] Check that there is no condensation or water droplets on the circuit board.

During Use

- [5] Be careful to not allow conductive objects to come into contact with the board.
- [6] Brief accidental contact or even bringing your hand close to the board may result in discharge and lead to severe injury or death.

Therefore, DO NOT touch the board with your bare hands or bring them too close to the board. In addition, as mentioned above please exercise extreme caution when using conductive tools such as tweezers and screwdrivers.

- [7] If used under conditions beyond its rated voltage, it may cause defects such as short-circuit or, depending on the circumstances, explosion or other permanent damages.
- [8] Be sure to wear insulated gloves when handling is required during operation.

After Use

- [9] The ROHM Evaluation Board contains the circuits which store the high voltage. Since it stores the charges even after the connected power circuits are cut, please discharge the electricity after using it, and please deal with it after confirming such electric discharge.
- [10] Protect against electric shocks by wearing insulated gloves when handling.

This evaluation board is intended for use only in research and development facilities and should by handled only by qualified personnel familiar with all safety and operating procedures.

We recommend carrying out operation in a safe environment that includes the use of high voltage signage at all entrances, safety interlocks, and protective glasses.

www.rohm.com HVB01E



Gate Driver

BM60212FV-C Evaluation Board

BM60212FV-EVK001

The BM60212FV-EVK001 board can be driving IGBT Power Devices for High-side and Low-side on Half-Bridge application.

The BM60212FV-C has Power Supply protections which are the Under-Voltage Lockout (UVLO) function at VCCA and VCCB. The Active Miller Clamping is included for gate control. The BM60212FV-EVK001 allows designers to evaluate Rohm's Gate Driver family for various applications.

Application

IGBT Gate Drive, MOSFET Gate Drive

Electric Characteristics

Features and electric characteristics are complied with BM60212FV-C. The BM60212FV-C datasheet can be referenced to help facilitate designs.

Operating Range

| Parameter | Symbol | Min | Тур | Max | Units |
|-----------------------------------|--------|---------|---------|---------|-------|
| High-side Floating Supply Voltage | Vcca | GND2+10 | GND2+15 | GND2+24 | V |
| Low-side Supply Voltage | Vccв | 10 | 15 | 24 | V |
| Operating Temperature | Topr | -40 | | +125 | °C |

Absolute Maximum Ratings

| Parameter | Symbol | Limits | Units |
|-------------------------------------|--------|--|-------|
| High-side Floating Supply Voltage | Vcca | -0.3 to +1230.0 ^(Note 1) | V |
| Low-side Supply Voltage | Vccв | -0.3 to +30.0 ^(Note 1) | V |
| Logic Input Voltage (INA, INB, ENA) | Vin | -0.3 to +V _{CCB} +0.3 or +30.0 ^(Note1) | V |

(Note 1): Relative to GND1

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Terminal Descriptions

| Pin name | Description | | |
|----------|--------------------------------------|--|--|
| VCCA | High-side power supply | | |
| VCCB | Low-side and input-side power supply | | |
| ENA | Input enabling signal input | | |
| INA | Control input pin for high-side | | |
| INB | Control input pin for low-side | | |
| GATE_L | Low-side Gate Control | | |
| GND1 | Low-side and input-side ground | | |
| GND2 | High-side ground | | |
| GATE_H | High-side Gate Control | | |

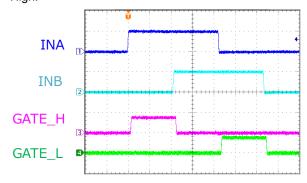
Input / Output terminal Control

| ENA (input) | INA (input) | INB (input) | GATE_H (Output) | GATE_L (Output) |
|----------------|----------------|----------------|--------------------|--------------------|
| L | X | X | L | L |
| Н | L | L | L | L |
| Н | L | Н | L | Н |
| Н | Н | L | Н | L |
| Н | Н | Н | L | L |

X: Don't care

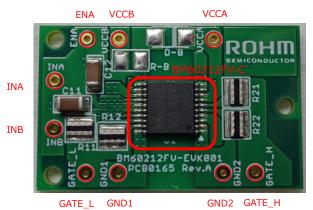
Waveform

When ENA = High:



Evaluation Board

Front



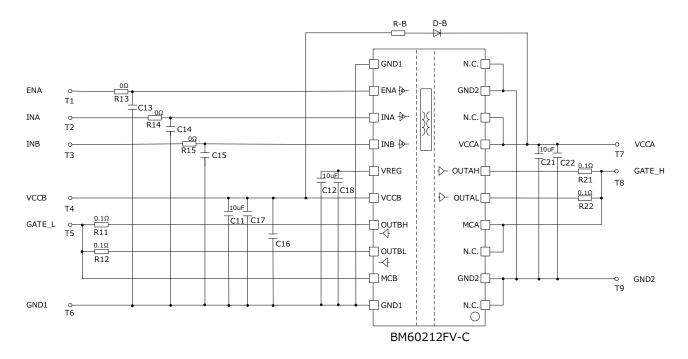
Back

33 mm

21 mm

Schematics

R11, R12, R13, R14, R15, R21, and R22 are implemented interim resisters for shipment check. Please replace each resister which can work with Power Device or input device appropriately.



Bill of Materials

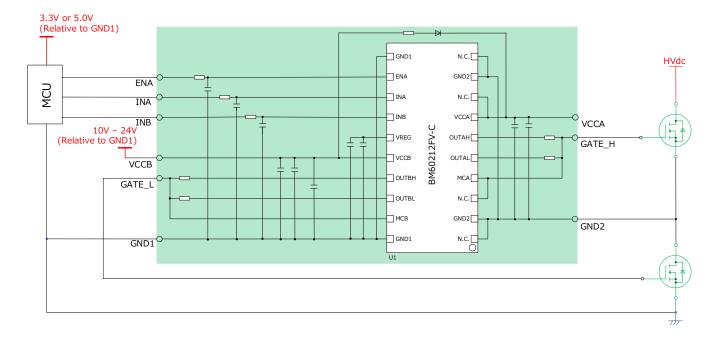
| | 1 | , | | |
|---|---|---|---|--|
| Parts Number | Description | Manufacturer | Parts name | Qty. |
| U1 | 2ch, 10-24V | ROHM | BM60212FV-C | 1 |
| C11 | 10μF, 50V, X7R, 3216 | TDK | CGA5L1X7R1H106K160 | 1 |
| C17 | (no stuff) | | | 0 |
| C21 | 10µF, 50V, X7R, 3216 | TDK | CGA5L1X7R1H106K160 | 1 |
| C22 | (no stuff) | | | 0 |
| C12 | 10µF, 50V, X7R, 3216 | TDK | CGA5L1X7R1H106K160 | 1 |
| C18 | (no stuff) | | | 0 |
| R13, R14, R15 | 0 ohm, 1608 | ROHM | MCR03EZPJ000 | 3 |
| C13, C14, C15 | (no stuff) | | | 0 |
| R11 | 0.1 ohm, 3216 | ROHM | LTR18EZPJLR10 | 1 |
| R12 | 0.1 ohm, 3216 | ROHM | LTR18EZPJLR10 | 1 |
| R21 | 0.1 ohm, 3216 | ROHM | LTR18EZPJLR10 | 1 |
| R22 | 0.1 ohm, 3216 | ROHM | LTR18EZPJLR10 | 1 |
| D-B | (no stuff) | | | 0 |
| R-B | (no stuff) | | | 0 |
| C16 | (no stuff) | | | 0 |
| T1, T2, T3, T4, T5, T6, T7, T8, T9 (Option) | (no stuff) | Hirosugi-Keiki | HT-0710-3 | 9 |
| (Option) | M2, 10mm | Hirosugi-Keiki | BSN2010 | 3 |
| (Option) | M2 | Hirosugi-Keiki | NNT-00 | 3 |
| | U1 C11 C17 C21 C22 C12 C18 R13, R14, R15 C13, C14, C15 R11 R12 R21 R22 D-B R-B C16 T1, T2, T3, T4, T5, T6, T7, T8, T9 (Option) (Option) | U1 2ch, 10-24V C11 10μF, 50V, X7R, 3216 C17 (no stuff) C21 10μF, 50V, X7R, 3216 C22 (no stuff) C12 10μF, 50V, X7R, 3216 C18 (no stuff) R13, R14, R15 0 ohm, 1608 C13, C14, C15 (no stuff) R11 0.1 ohm, 3216 R12 0.1 ohm, 3216 R21 0.1 ohm, 3216 R22 0.1 ohm, 3216 C18 (no stuff) R11 (no stuff) C10 (no stuff) C11, T2, T3, T4, T5, T6, T7, T8, T9 (Option) (Option) M2, 10mm | U1 2ch, 10-24V ROHM C11 10μF, 50V, X7R, 3216 TDK C17 (no stuff) C21 10μF, 50V, X7R, 3216 TDK C22 (no stuff) C12 10μF, 50V, X7R, 3216 TDK C18 (no stuff) R13, R14, R15 0 ohm, 1608 ROHM C13, C14, C15 (no stuff) R11 0.1 ohm, 3216 ROHM R12 0.1 ohm, 3216 ROHM R21 0.1 ohm, 3216 ROHM R22 0.1 ohm, 3216 ROHM C13, C14, C15 (no stuff) R15 (no stuff) R16 (no stuff) R17 (10 stuff) R17 (11 characteristics) R18 (no stuff) R19 (Option) R10 M2, 10mm Hirosugi-Keiki | U1 2ch, 10-24V ROHM BM60212FV-C C11 10μF, 50V, X7R, 3216 TDK CGA5L1X7R1H106K160 C17 (no stuff) CGA5L1X7R1H106K160 C21 10μF, 50V, X7R, 3216 TDK CGA5L1X7R1H106K160 C12 10μF, 50V, X7R, 3216 TDK CGA5L1X7R1H106K160 C18 (no stuff) CGA5L1X7R1H106K160 C18 (no stuff) MCR03EZPJ000 C13, R14, R15 0 ohm, 1608 ROHM MCR03EZPJ000 C13, C14, C15 (no stuff) LTR18EZPJLR10 R11 0.1 ohm, 3216 ROHM LTR18EZPJLR10 R21 0.1 ohm, 3216 ROHM LTR18EZPJLR10 R22 0.1 ohm, 3216 ROHM LTR18EZPJLR10 D-B (no stuff) LTR18EZPJLR10 R-B (no stuff) Hirosugi-Keiki HT-0710-3 T1, T2, T3, T4, T5, T6, T7, T8, T9 (Option) Hirosugi-Keiki HT-0710-3 (Option) M2, 10mm Hirosugi-Keiki BSN2010 |

Materials may be changed without notice.

Application and Operation procedure

Following figure is shown the example application. IGBT [Power Device] and microcontroller [MCU] are connected to the board via terminals. VCCA power can be supplied from VCCB by using bootstrap circuit. Please place appropriate components on the EVK for bootstrap. Please make sure to replace the appropriate value for each resistor and capacitor on the board depends on your applications. The numerous application notes can be referenced to help facilitate designs. Useful application notes are listed on page 7.

Example Application

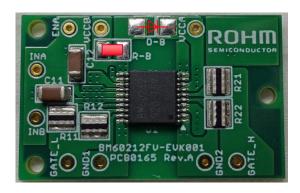


Additional Components for Bootstrapping

R-B and D-B parts are for bootstrapping. Place appropriate components depends on your applications. Examples:

D-B: ROHM RFN2LAM6STF [Reverse voltage: 600V, Current: 1.5A, Package: PMDTM]

R-B: ROHM ESR18 series resistor [Package size: 3216mm]



Equipment

- DC Power Supply: 5 V or 3.3V for control signal [5 VDC], 10 to 24 V for Power Device [10 to 24 VDC]
- · Microcontroller [MCU]: Input signal for controlling GATE_H and GATE_L outputs
- Power Device: IGBT

We have many power devices which can work with Evaluation Board. You can get applicable product information from our web site. Some products are shown on page 7.

Instructions

Before start to connect, make sure to turn off all equipment for your safety.

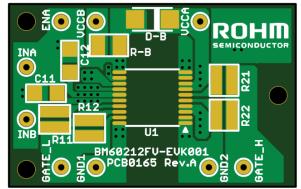
- 1. Connect 5 VDC to VCC1-GND1 terminal on board.
 - Stay turn off the power supply.
- 2. Connect 10 to 24 VDC to VCC2-GND2 terminal on board.
 - Stay turn off the power supply.
- 3. Connect MCU to the ENA, INA, and INB terminal on board. Refer to the Input / Output terminal Control description on page 2.
- 4. Connect GATE H and GATE L terminal on board to gate terminals on high-side and low-side power devices.
- 5. Turn on the 5 VDC and MCU.
- 6. Turn on the 10 to 24 VDC.

PCB Layout

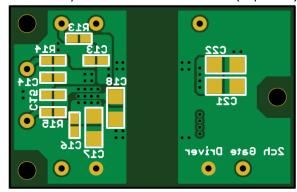
Board size: 33 x 21 mm, Material: FR-4, 4-layer.

Input-side capacitors and output capacitors [C16, C17, C18, C21, and C22] are placed on bottom side in order to reduce board size. When you design your PCB layout, we recommend to place them to the same side and near the gate driver as close as possible.

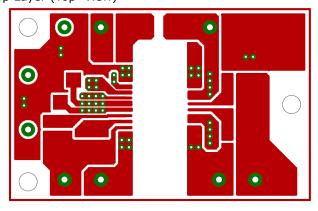
Top Layer with Pad and Silkscreen (Top View)



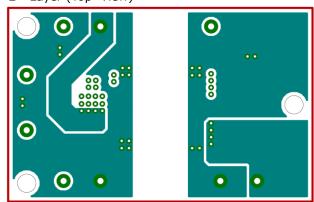
Bottom Layer with Pad and Silkscreen (Top View)



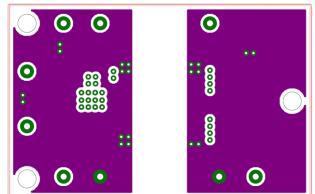
Top Layer (Top View)



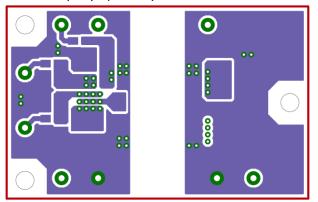
2nd Layer (Top View)



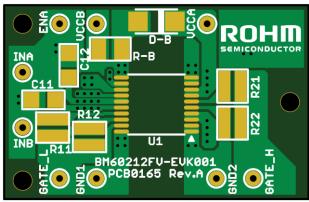
3rd Layer (Top View)



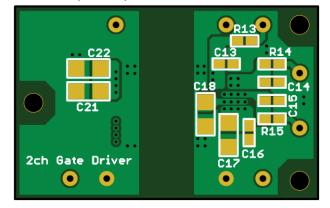
Bottom Layer (Top View)



Silkscreen (Top)



Silkscreen (Bottom)



We have numerous power devices which are suitable for your requests. For the IGBT, please visit our web site below: https://www.rohm.com/products/igbt

Following examples are IGBT for high speed fast switching with fast recovery diode.

| Matching Parts | V _{CES} [V] | I _C [A] (100°C) | V _{CE} (SAT) (Typ.)[V] | tf(Typ.) [ns] | Diode | Package |
|----------------|----------------------|-------------------------------|------------------------------------|------------------|-------|---------|
| RGW40TS65D | | 20 | | 63 | | |
| RGW50TS65D | | 25 | | 53 | | |
| RGW60TS65D | | 30 | | 35 | | TO-247N |
| RGW80TS65D | | 40 | 1.5 | 34 | FRD | 10-247N |
| RGW00TS65D | 650 | 50 | | 33 | | |
| RGWX5TS65D | | 75 | | 31 | | |
| RGW40TK65D | | 16 | 1.5 | 63 | ראט | |
| RGW50TK65D | | 18 | | 53 | | |
| RGW60TK65D | | 20 | | 35 | | TO 2DEM |
| RGW80TK65D | | 23 | | 34 | | TO-3PFM |
| RGW80TK65E | | 23 | | 34 | | |
| RGW00TK65D | | 26 | | 33 | | |

We also offer useful power device application notes for design and evaluation. Please visit our web site below:

https://www.rohm.com/search/application-notes

- 1. Gate-source voltage behavior in a bridge configuration, No.60AN135E
- 2. Gate-Source Voltage Surge Suppression Methods, No.62AN010E
- 3. Snubber circuits design method for SiC MOSFET, No.62AN037E
- 4. Switching Loss improvement by TO-247-4L with Driver Source, No.62AN04E

Revision History

| Date | Revision Number | Description |
|---------|-----------------|-------------|
| 2019.10 | 001 | |

Notes

- 1) The information contained herein is subject to change without notice.
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